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March 26, 2003

Atty Docket No.: JCLA5827-R
Appl. No. : 09/586,525
Filing Date : June, 02, 2000
Pages : Cover + 7

BY FACSIMILE ONLY

Fax No. : 703-872-9318
Attention : Examiner NADAV, ORI
Group Unit : 2811
From : Jiawei Huang, Reg. No. 43,330
MESSAGE : Enclosed is an Amendment in 7 pages.

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on **March 26, 2003** at the above indicated fax number.

Sign by: 
Michelle Chang

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Docket No. JCLA5827-R
US App. No. 09/586,525

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : YING CHOU TSAI et al.

- Application No. : 09/586,525

Filed : June 2, 2000

For : SUBSTRATE STRUCTURE OF FLIP CHIP
PACKAGE

Examiner : NADAV, ORI

Attorney Docket No. : JCLA5827-R

10/C
J. Markley
3-28-03
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AMENDMENT

Assistant Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated December 30, 2002, please enter the following amendments and consider the following remarks:

In the Claims:

Please amend claims 1 and 7 as follows:

- CX PI*
1. (Third time amended) A substrate structure of Flip Chip package comprising:
a plurality of patterned circuit layers;

at least an insulative layer stacked between the patterned circuit layers for isolating the patterned circuit layers, wherein the patterned circuit layers are electrically connected one another, and one of the patterned circuit layers is positioned on the surface of the substrate of the flip chip package as a top patterned circuit layer, and the top patterned circuit layer comprises at least a plurality of first mounting pads and a plurality of second mounting pads; and
a solder mask layer covering the patterned circuit layer on the surface of the substrate of